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Dated: May 1, 2003

Signature: *Daryl K. Jeff*  
(Daryl K. Jeff)

#9/C  
5/21/03

Docket No.: TESSERA 3.0-113 CONT  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

*V. Hart*

In re Patent Application of:  
Belgacem Haba

Application No.: 09/602,951

Filed: June 23, 2000

For: METHOD FOR FORMING A MULTI-  
LAYER CIRCUIT ASSEMBLY

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: Group Art Unit: 3729  
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: Examiner: Rick K. Chang  
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Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

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TECHNOLOGY CENTER

AMENDMENT

Dear Sir:

In response to the Official Action mailed November 1, 2002, Applicant submits the following amendments and remarks.

IN THE CLAIMS

1. (Amended) A method of making a multi-layer circuit assembly comprising the steps of:

(a) providing a core structure including an inner dielectric element having first and second metal layers on opposite surfaces thereof;

(b) forming one or more through vias extending through said metal layers and said inner dielectric element;

(c) coating said metal layers and said through vias with a dielectric material to thereby form a coated structure having first and second outer dielectric layers overlying the first and second metal layers respectively and dielectric material lining said through vias;

(d) providing outer metal layers over said first and